

Date: November 2025
Rev: VI
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.12 Part B: 1.18
Pot Life: 3 Days
Shelf Life- Bulk: Six months at room temperature

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):

May not achieve performance properties listed below

150°C / 10 Minutes

120°C / 30 Minutes

80°C / 2 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**

Product Description: EPO-TEK® 354-T2 is a two component, thixotropic, high Tg epoxy designed for semiconductor packaging in medical, fiber optic and optoelectronic assemblies. It is an electrically and thermally insulating epoxy and a more thixotropic version of EPO-TEK® 354-2.

Typical Properties: Cure condition: varies as required Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

Information is Preliminary While Specifications Are Being Developed.

PHYSICAL PROPERTIES:				
*Color (before cure):	Part A: Tan	Part B: Dark Amber		
*Consistency:	Smooth Thixotropic Paste			
*Viscosity (23°C) @ 10 rpm:	20,008	cPs		
*Thixotropic Index:	2.85			
*Glass Transition Temp:	111	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):				
	Below Tg:	68.6	x 10 ⁻⁶ in/in°C	
	Above Tg:	393.7	x 10 ⁻⁶ in/in°C	
Shore D Hardness:	82			
Die Shear @ 23°C:	≥20	Kg	7112	psi
Lap Shear @ 23°C:	1513	psi		
Degradation Temp:	430	°C		
Weight Loss:				
	@ 200°C:	0.02	%	
	@ 250°C:	0.17	%	
	@ 300°C:	0.45	%	
Suggested Operating Temperature:	< 300	°C (Intermittent)		
Storage Modulus:	286739.6	psi		
*Particle Size:	≤ 20	microns		

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	N/A			
Volume Resistivity @ 23°C:	≥1 x 10 ¹⁶	Ohm-cm		
Dielectric Constant (1KHz):	2.26			
Dissipation Factor (1KHz):	0.004			

OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission:	>90% @ 2100- 600	nm		
Refractive Index:	1.5725	nm		

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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